L Number	Hits	Search Text	DB	Time stamp
1	114566	photolithography or lithography	USPAT;	2004/08/03 17:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	1508272	mold\$3 or mould\$3	USPAT;	2004/08/03 17:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
i			IBM_TDB	
3	9260	(photolithography or lithography) and (mold\$3 or	USPAT;	2004/08/03 17:58
		mould\$3)	US-PGPUB;	
		· .	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	36986	65/\$.ccls.	USPAT;	2004/08/03 17:58
7	00300	ου, φ. σσ. σ.	US-PGPUB;	2004/00/00 17:00
			EPO; JPO;	
			DERWENT;	
_	70	(/whatalithannanhu an lithannanhu) and (mald\$2 an	IBM_TDB	2004/09/03 47.50
5	70	((photolithography or lithography) and (mold\$3 or	USPAT;	2004/08/03 17:59
		mould\$3)) and 65/\$.ccls.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	:
_			IBM_TDB	
7	819	fluorine and ((photolithography or lithography) and	USPAT;	2004/08/03 17:59
		(mold\$3 or mould\$3))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	22	fluorine and (((photolithography or lithography) and	USPAT;	2004/08/03 18:00
		(mold\$3 or mould\$3)) and 65/\$.ccls.)	US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	1810	fluorine same (sinter\$ or consolidat\$)	USPAT;	2004/08/03 18:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	20	(fluorine same (sinter\$ or consolidat\$)) and	USPAT;	2004/08/03 18:31
		((photolithography or lithography) and (mold\$3 or	US-PGPUB;	1
		mould\$3))	EPO; JPO;	
		1 ""	DERWENT;	
			IBM_TDB	
10	8	09/397573	USPAT;	2004/08/03 18:30
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
44	107	(photolithography or lithography) and (fluoring	USPAT;	2004/08/03 18:31
11	107	(photolithography or lithography) and (fluorine	•	2004/00/03 10.31
		same (sinter\$ or consolidat\$))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
10		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	IBM_TDB	0004/00/07 15 7
12	20	((fluorine same (sinter\$ or consolidat\$)) and	USPAT;	2004/08/03 18:33
		((photolithography or lithography) and (mold\$3 or	US-PGPUB;	
		mould\$3))) and (remov\$4 or etch\$6 or cut\$4 or	EPO; JPO;	
		abrad\$5 or polish\$3)	DERWENT;	
			IBM_TDB	

13	20	((fluorine same (sinter\$ or consolidat\$)) and	USPAT;	2004/08/03 18:33
		((photolithography or lithography) and (mold\$3 or	US-PGPUB;	
		mould\$3))) and (remov\$4 or etch\$6 or cut\$4 or	EPO; JPO;	
		abrad\$5 or polish\$3) and surface	DERWENT;	
			IBM_TDB	
14	20	((fluorine same (sinter\$ or consolidat\$)) and	USPAT;	2004/08/03 18:44
		((photolithography or lithography) and (mold\$3 or	US-PGPUB;	
		mould\$3))) and (remov\$4 or etch\$6 or cut\$4 or	EPO; JPO;	
		abrad\$5 or polish\$3) and surface	DERWENT;	
		l	IBM_TDB	
15	8986	(photolithography or lithography) and (fluorine or	USPAT;	2004/08/03 18:45
		siF.\$)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	200004		IBM_TDB	0004/00/00 40.54
16	238934	surface near2 (grind\$4 or ground\$3 or polish\$4 or	USPAT;	2004/08/03 18:51
		abrad\$5 or etch\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
47	0070	((nhatalithagraphy an lithagraphy) and (flugging a	IBM_TDB	2004/09/02 49:47
17	2378	((photolithography or lithography) and (fluorine or siF.\$)) and (surface near2 (grind\$4 or ground\$3 or	USPAT; US-PGPUB;	2004/08/03 18:47
		polish\$4 or abrad\$5 or etch\$3))	EPO; JPO;	
			DERWENT;	
18	22	65/\$.ccls. and (((photolithography or lithography)	IBM_TDB USPAT;	2004/08/03 18:47
10		and (fluorine or siF.\$)) and (surface near2 (grind\$4	1	2004/06/03 16.47
		or ground\$3 or polish\$4 or abrad\$5 or etch\$3)))	US-PGPUB; EPO; JPO;	
		or groundes or polisher or abrades or etches)))	DERWENT;	
			1	
19	266758	surface near2 (grind\$4 or ground\$3 or abrad\$5 or	IBM_TDB USPAT;	2004/08/03 19:03
19	200758	remov\$4)	US-PGPUB;	2004/00/03 18.03
		1 Citi	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
20	1656	(surface near2 (grind\$4 or ground\$3 or abrad\$5 or	USPAT;	2004/08/03 18:52
		remov\$4)) and ((photolithography or lithography)	US-PGPUB;	
		and (fluorine or siF.\$))	EPO; JPO;	
		,	DERWENT;	
			IBM_TDB	
21	120480	surface near2 (grind\$4 or ground\$3 or abrad\$5)	USPAT;	2004/08/03 18:52
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
22	1656	((photolithography or lithography) and (fluorine or	USPAT;	2004/08/03 18:53
		siF.\$)) and (surface near2 (grind\$4 or ground\$3 or	US-PGPUB;	
		abrad\$5 or remov\$4))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
23	197	((photolithography or lithography) and (fluorine or	USPAT;	2004/08/03 19:02
		siF.\$)) and (surface near2 (grind\$4 or ground\$3 or	US-PGPUB;	
		abrad\$5))	EPO; JPO;	1
			DERWENT;	
			IBM_TDB	
24	333	(mold\$3 or mould\$3) and (((photolithography or	USPAT;	2004/08/03 19:02
		lithography) and (fluorine or siF.\$)) and (surface	US-PGPUB;	
		near2 (grind\$4 or ground\$3 or polish\$4 or abrad\$5	EPO; JPO;	
		or etch\$3)))	DERWENT;]
			IBM_TDB	
25	1	(mold\$3 or mould\$3) and II22	USPAT;	2004/08/03 19:02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1		IBM_TDB	1

26	258	(mold\$3 or mould\$3) and (((photolithography or	USPAT;	2004/08/03 19:02
		lithography) and (fluorine or siF.\$)) and (surface	US-PGPUB;	
		near2 (grind\$4 or ground\$3 or abrad\$5 or	EPO; JPO;	
		remov\$4)))	DERWENT;	
			IBM_TDB	
27	157999	surface near (grind\$4 or ground\$3 or abrad\$5 or	USPAT;	2004/08/03 19:03
		remov\$4)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
28	11	(surface near2 (grind\$4 or ground\$3 or polish\$4 or	USPAT;	2004/08/03 19:04
		abrad\$5 or etch\$3)) near4 ingot and	US-PGPUB;	
		(photolithography or lithography)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	